## SMD Multilayer Ferrite Chip Beads

SB/PB/NB/GB/UPB/BA Series

1-1.Mechanical Performances

No	Item	Specification	Test Method		
1-1-1	Flexure Strength	The forces applied on the right conditions must not damage the terminal electrode and the ferrite	Test device shall be soldered on the substrate Substrate Dimension: 100x40x1.6mm Deflection: 2.0mm Keeping Time: 30sec *For 100505, substrate dimension is 100x40x0.8mm		
1-1-2	Vibration		Test device shall be soldered on the substrate Oscillation Frequency: 10 to 55 to 10Hz for 1min Amplitude: 1.5mm Time: 2hrs for each axis (X, Y & Z), total 6hrs		
1-1-3	Resistance to Soldering Heat	Appearance: No damage More than 75% of the terminal electrode should be covered with solder. Impedance: within £0% of initial value	Pre-heating: 150 , 1min  Solder Composition: Sn / Pb = 63/37  Solder Composition:Sn/Ag3.0/Cu0.5(Pb-Free)  Solder Temperature: 260 ±6  Immersion Time: 10 ±1sec		
1-1-4	Solder ability	The electrodes shall be at least 90% covered with new solder coating	Pre-heating: 150 , 1min  Solder Composition: Sn / Pb = 63/37  Solder Temperature: 220 £  Solder composition:Sn/Ag3.0/Cu0.5(Pb-Free)  Solder Temperature:245 £ (Pb-Free)  Immersion Time: 4 £l sec		
1-1-5	Terminal Strength Test	100505 series: 0.2 kg 160808 series: 0.5 kg 201209 series: 1.0 kg other series: 2.0 kg (BAY/BAQ)321609 series: 1.5 kg (Push)	Test device shall be soldered on the substrate		

## Reliability Test - SB/PB/NB/GB/UPB/BA Series

## 1-2.Environmental Performances

No	Item	Specification	Test Method					
1-2-1	Temperature Cycle	Appearance: No damage	One cycle:					
		Impedance: within ±30% of initial	Ste	ер	Temperature ( )	Time (min)		
		value	1		-55 £	30		
			2		25 €	3		
			3		125 £	30		
			4		25 €	3		
			Total: 100cycles  Measured after exposure in the room condition for 24hrs					
1-2-2	Humidity		: 40 <del>2</del>					
	Resistance		Relativ	Relative Humidity: 90 ~ 95%				
			Time: 1000hrs					
			Measu	red af	ter exposure in the roo	24hrs		